



DATASHEET

ES-2835-053V-L1-XXXX

ES-2835-053V-L1-XXXX Datasheet

This 2835 LED Light Source is a high performance energy efficient device which can handle high thermal and high driving current. The small package outline and high intensity make it an ideal choice for LED panel light, LED bulb light, LED tube light, backlighting and etc.

This part has a foot print that is compatible to most of the same size LED in the market today



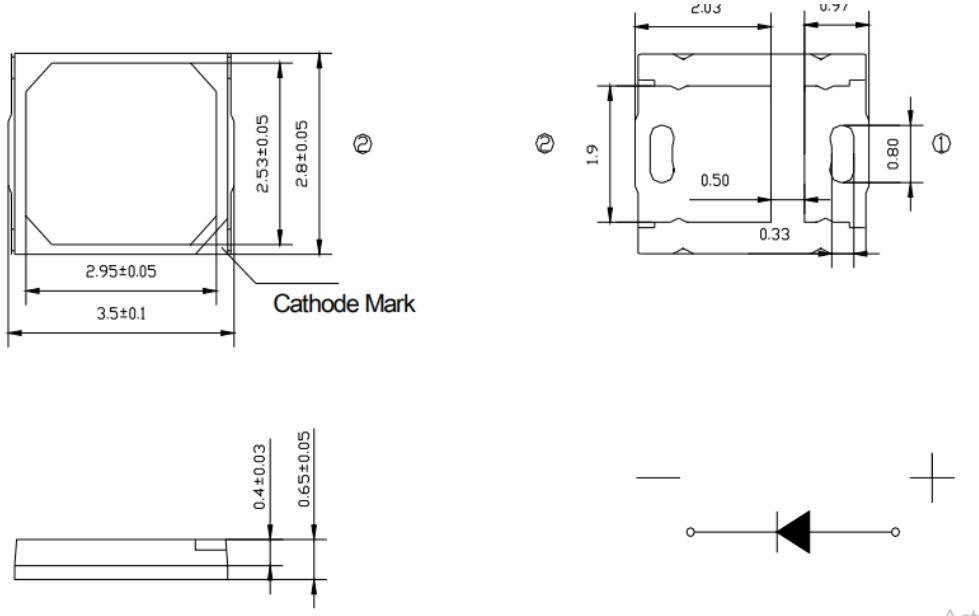
FEATURES

- Available in Cool White, Neutral White and Warm White color
- ANSI-compatible chromaticity bins
- High luminous Intensity and high efficiency
- Compatible with reflow soldering process
- Low thermal resistance
- Long operation life
- Wide viewing angle at 120°
- Silicone encapsulation
- Environmental friendly, RoHS compliance

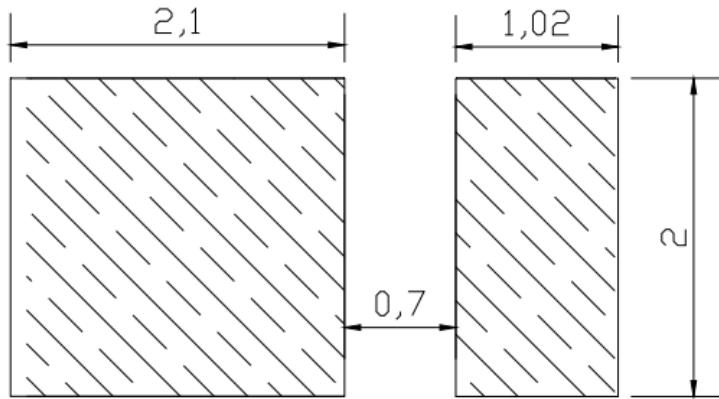
APPLICATIONS

- Flat panel light
- Backlighting
- LED tube light
- LED bulb light
- Interior & exterior automotive lighting
- Decorative and landscape lighting
- Signage and channel letter
- Reading lamp
- Decorating and entertainment lighting
- Architectural lighting

PACKAGE DIMENSIONS



Recommended Solder Pad Design



Notes:

1. All dimensions in millimeters.
2. Thickness tolerance of copper plate is ±0.02mm.
3. Thickness tolerance of product is ±0.05mm.
4. Tolerance is ±0.1mm unless otherwise noted.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Forward current	I _F	150	mA
Peak Forward Current	I _{FP}	300	mA
Reverse Voltage	V _R	5	V
Power Dissipation	P _d	500	mW
Operating Temperature	T _{opr}	-40~+85	°C
Storage Temperature	T _{stg}	-40~+100	°C
Soldering Temperature	T _{sld}	Reflow Soldering: 260°C for 10 seconds	
LED Junction Temperature	T _j	125	°C

I_{FP} Conditions: Pulse Width ≤10msec. and Duty ≤1/10.

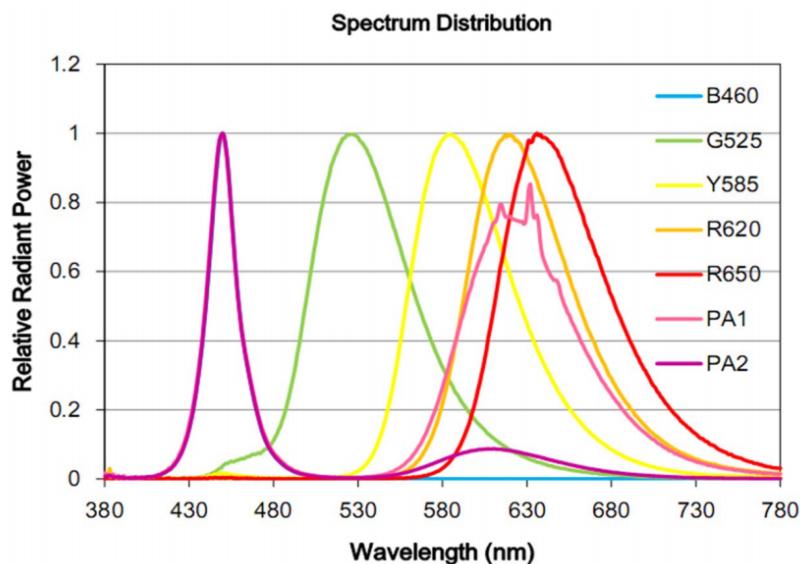
CHARACTERISTICS (T_j=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	IF=150mA	2.8	3.0	3.4	V
Viewing Angle	2θ _{1/2}	IF=150mA	--	120	--	deg.
Luminous Flux	Φ _v	IF=150mA	9	--	95	lm
Thermal Resistance (Junction to Solder Point)	R _{th-jS}	IF=150mA	--	30	--	°C/W

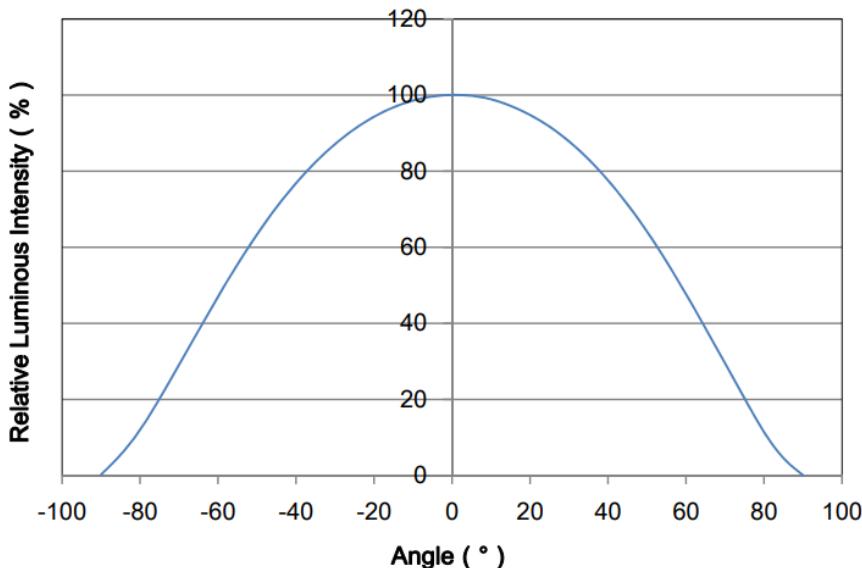
Notes:

1. Luminous flux is measured with an accuracy of ± 10%.
2. Chromaticity coordinate bins are measured with an accuracy of ± 0.01.
3. All measurements were made under the standardized environment of Everstar

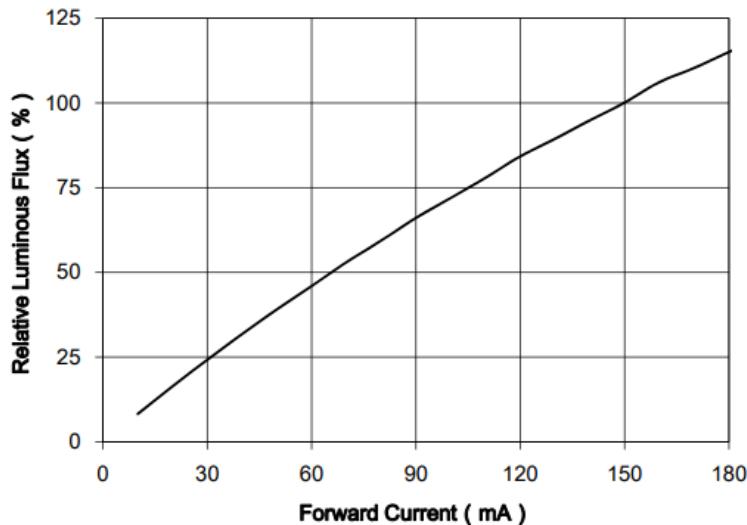
RELATIVE SPECTRAL POWER DISTRIBUTION ($T_j=25^\circ\text{C}$)



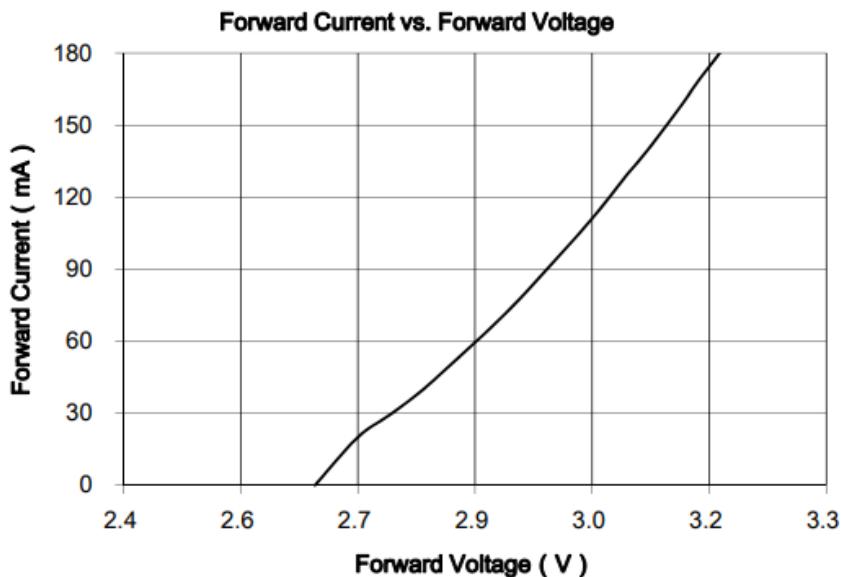
TYPICAL SPATIAL DISTRIBUTION



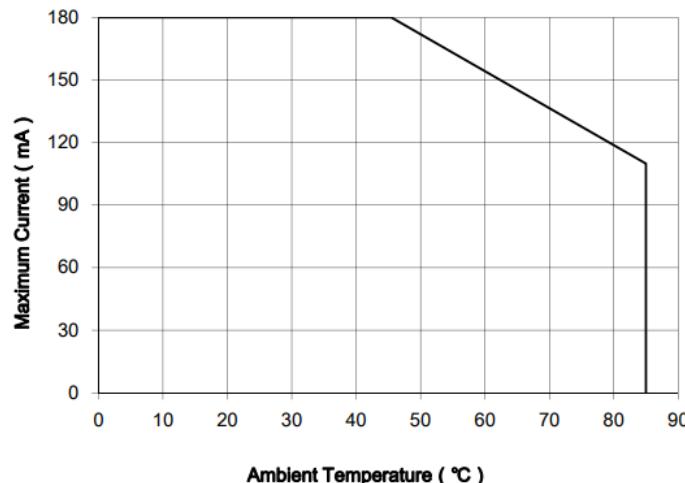
RELATIVE LUMINOUS FLUX VS. CURRENT ($T_j=25^\circ\text{C}$)



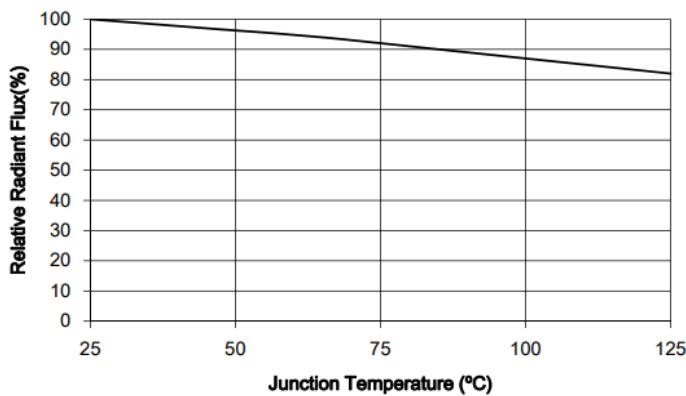
ELECTRICAL CHARACTERISTICS ($T_j=25^\circ\text{C}$)



MAXIMUM CURRENT VS. AMBIENT TEMPERATURE



RELATIVE RADIANT FLUX VS. JUNCTION TEMPERATURE



SORTING RANKS**(1) Luminous Intensity (Tj=25°C)**

Part No.	Condition	Rank	Unit
ES-2835-053V-L1-R637		L1 14-19	
ES-2835-053V-L1-G525		L1 85-95	
ES-2835-053V-L1-B460	150mA	L1 9-12	Im
ES-2835-053V-L1-P01P		L1 45-55	
ES-2835-053V-L1-Y585		L1 60-70	

(2) Forward Voltage (Tj=25°C)

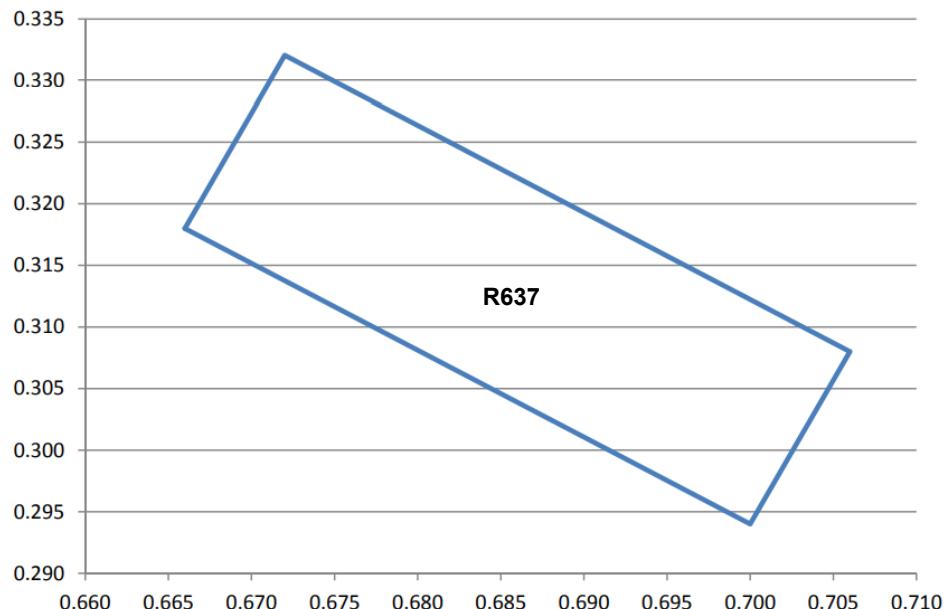
Rank	Condition	Min.	Max.	Unit
V1		2.8	3.0	
V2	150mA	3.0	3.2	V
V3		3.2	3.4	

Notes:

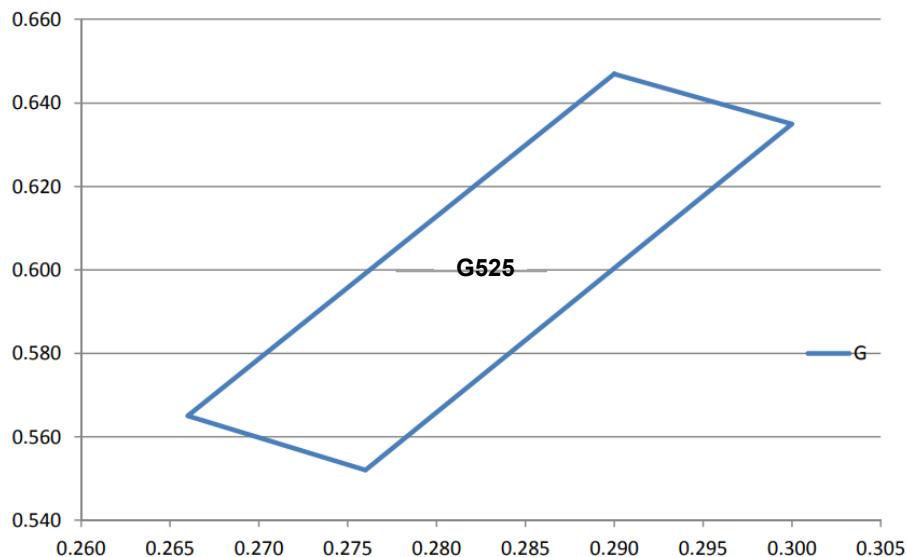
1. 10% tolerance for luminous intensity may be caused by measurement inaccuracy.
2. Measurement Uncertainty of the Forward Voltage : $\pm 3\%$

(3) Chromaticity Bins

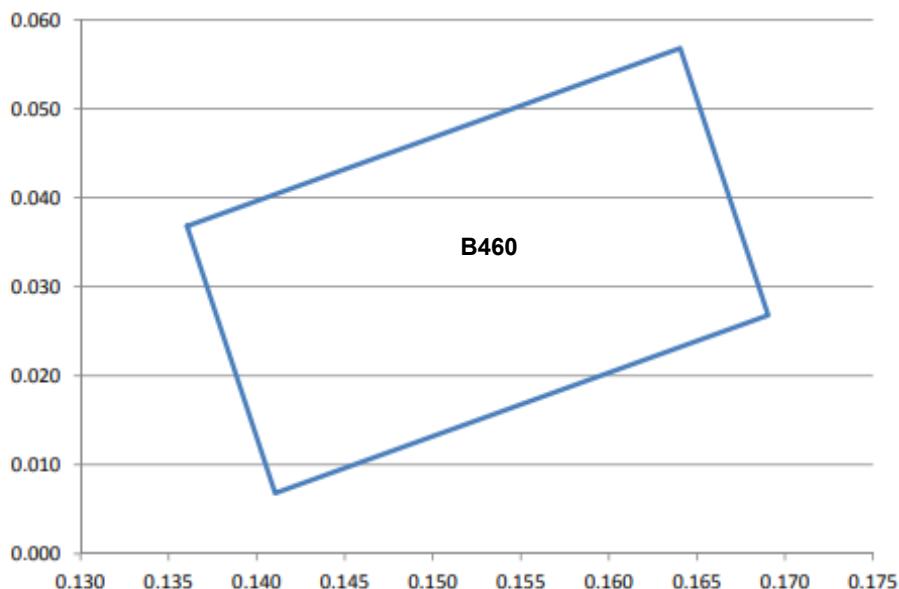
Rank	ES-2835-053V-L1-R637				
Bin Code	Color Coordinates(X,Y)				
R637	X	0.6660	0.6720	0.7060	0.7000
	Y	0.3180	0.3320	0.3080	0.2940



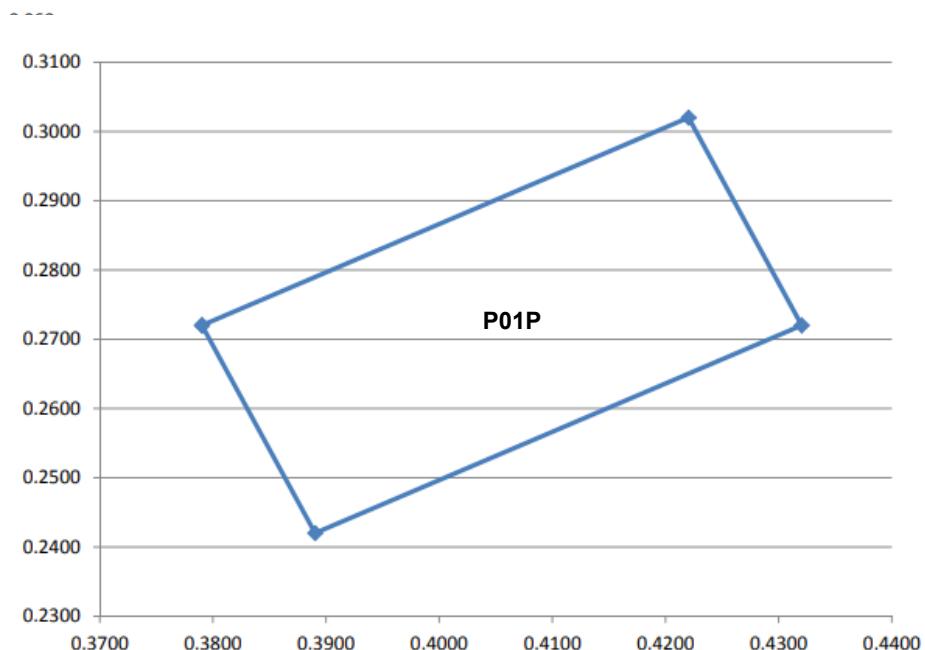
Rank	ES-2835-053V-L1-G525				
Bin Code	Color Coordinates(X,Y)				
G525	X	0.2900	0.2660	0.2760	0.3000
	Y	0.6470	0.5650	0.5520	0.6350



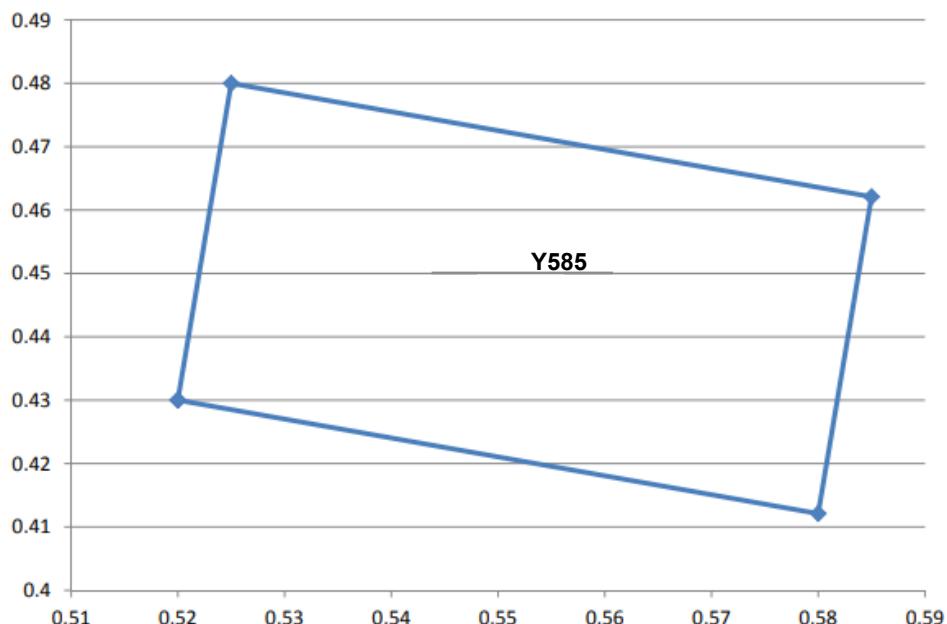
Rank	ES-2835-053V-L1-B460				
Bin Code	Color Coordinates(X,Y)				
B460	X	0.1361	0.1411	0.1691	0.1641
	Y	0.0368	0.0068	0.0268	0.0568



Rank	ES-2835-053V-L1-P01P				
Bin Code	Color Coordinates(X,Y)				
P01P	X	0.3790	0.3890	0.4320	0.4220
	Y	0.2720	0.2420	0.2720	0.3020



Rank	ES-2835-053V-L1-Y585				
Bin Code	Color Coordinates(X,Y)				
Y585	X	0.52	0.58	0.585	0.525
Y585	Y	0.43	0.4121	0.4621	0.48



REFLOW SOLDERING CHARACTERISTICS

For Reflow Process

Preheating : $140^{\circ}\text{C} \sim 160^{\circ}\text{C} \pm 5^{\circ}\text{C}$, within 2 minutes.

Operation heating : 260°C (Max.) within 10 seconds.(Max)

Gradual Cooling (Avoid quenching).

Lead solder		Lead-free solder	
Pre-heat	$120\text{-}150^{\circ}\text{C}$	Pre-heat	$150\text{-}200^{\circ}\text{C}$
Pre-heat time	120 sec.Max.	Pre-heat time	120 sec.Max.
Peak Temperature	240°C Max.	Peak Temperature	260°C Max.
Soldering time condition	10 sec.Max.	Soldering time condition	10 sec.Max.

Lead Solder

2.5~5 °C / sec.

Pre-heating $120\text{-}150^{\circ}\text{C}$

120sec. Max.

240 °C Max.

10 sec. Max.

60sec. Max. Above 200°C

Lead-free Solder

1~5 °C / sec.

Pre-heating $150\text{-}200^{\circ}\text{C}$

120sec. Max.

260 °C Max.

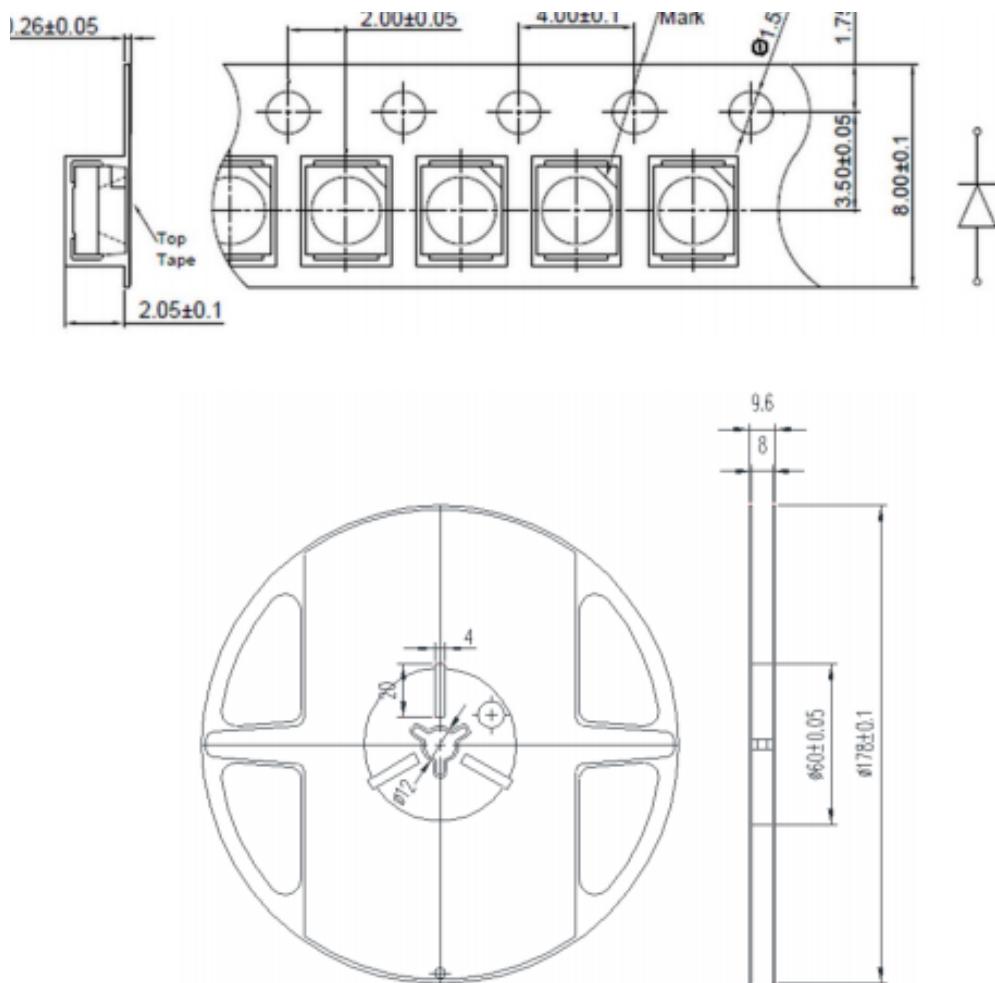
10 sec. Max.

60sec. Max. Above 220°C

Notes:

The encapsulated material of the LEDs is silicone . Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when using the picking up nozzle, the pressure on the silicone resin should be proper.

TAPE AND REEL

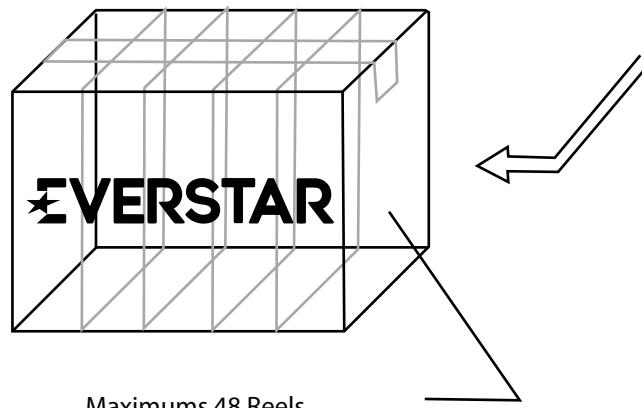
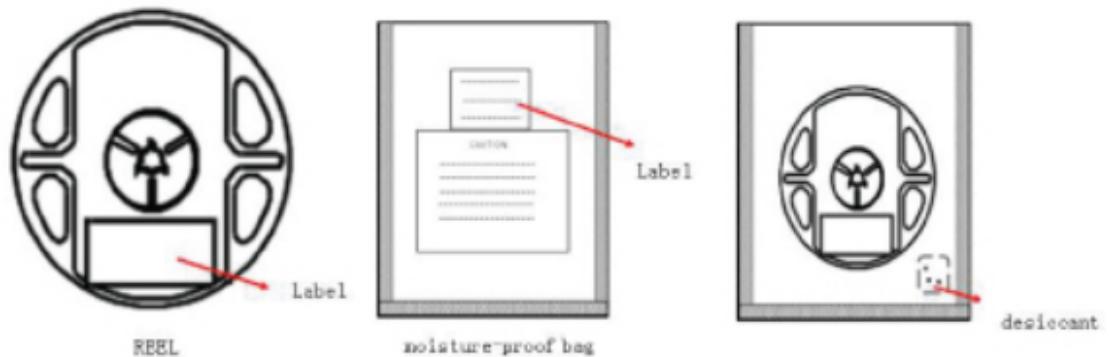


Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit=mm

Notes:

- (1) Quantity : 4,000pcs/Reel
- (2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be $\pm 0.2\text{mm}$
- (3) Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10° to the carrier tape
- (4) Package : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package.

PACKAGING



RELIABILITY TEST ITEMS

Test Items	Test Duration	Number of Damaged
Steady State Operating Life of High Temperature (HTOL) Ts=85°C, IF=Max	1000hrs	0/20
Steady State Operating Life of Low Temperature (LTOL) Ta=-40°C, IF=Max	1000hrs	0/20
Pulse Wet Operating Life of High Temperature (PWHTOL) 60°C/90%RH, IF 30mins ON/30min OFF	500hrs	0/20
High Temperature Storage (HTS) °C 80°C	1000hrs	0/20
Low Temperature Storage (LTS) -40°C	1000hrs	0/20
Thermal Shock (TS) -45°C~125°C 30min dwell 20sec transfer	100cycles	0/20
Solder Resistance (SR) 265°C, 3X MSL	5sec	0/20
Solder Ability (SA) 245°C 5sec, 95% coverage	5sec	0/11
Mechanical Shock (MS) 1500G 0.5msec pulse shock	Each 6 axis	0/6
Random Vibration (RV) 6G RMS, 10-2000Hz, 10min	Per axis	0/6
Variable Vibration Frequency (VVF) 10-2000-10Hz, log or linear sweep rate, 20G for 1 min, 1.5mm each apply 3x per axis over	6hrs	0/6
Salt Spread (SS) 35°C, 30g/m ² /day	48hrs	0/11

Item	Symbol	Test Condition	Criteria for Judgment
			Min. Max.
Forward	VF	IF=Typical Current	U.S.L x1.1
Luminous Flux	Im	IF=Typical Current	L.S.L x0.7
CCX&CCY	x.y	IF=Typical Current	Shift<0.02

PRECAUTION FOR USE

- (1) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When washing is required, IPA should be used.
- (2) When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.
- (3) LEDs must be stored to maintain a clean atmosphere. If the LEDs are stored for 3months or more after being shipped from Everstar, a sealed container with a nitrogen atmosphere should be used for storage.
- (4) The LEDs must be used within seven days after opening the moisture proof packing. Repack unused Products with anti-moisture packing, fold to close any opening and then store in a dry place.
- (5) The appearance and specifications of the product may be modified for improvement without notice.
- (6) This LED is sensitive to the static electricity and surge. It is recommended to use a wrist Band or anti-electrostatic glove when handling the LEDs.
- (7) On manual soldering, a solder tip must be needed as grounded for usage. If over voltage which exceeds the absolute maximum rating is applied to LEDs, it will cause damage LEDs and result in destruction. Damaged LEDs will show some unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LEDs get unlighted at low current.